

# SEMICON<sup>®</sup> KOREA

“ SEMICON KOREA 2018 에 초대합니다.”

TESCAN KOREA는 TESCAN사의 최신 Gallium FIB (Model : S8000G)를 부스에 설치, 저 가속에서 고 분해능 이미지, 기존 Ga - FIB 보다 약 2배 빠른 Milling Rate 등 우수한 장비 성능을 선보일 예정 입니다. 전시 기간 중 샘플 시연도 가능하오니, 샘플 DEMO를 원하시는 고객분께서는 샘플 정보 등을 미리 전달해 주시면 감사하겠습니다.

일 정: 2017년 01월 31일(수) - 02월 02일(금)  
시 간: 10:00~17:00 (수, 목) / 10:00~14:00 (금)  
장 소(Tescan Booth) : COEX 3층 D홀 No. D904

## TESCAN S8000G

New generation of FIB-SEM microscope

Field-free UHR



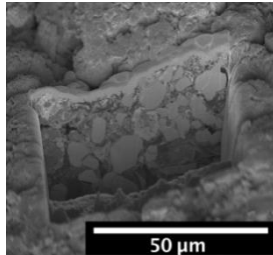
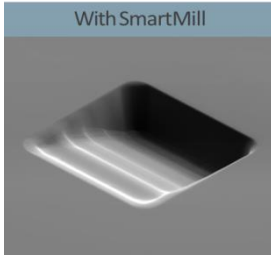
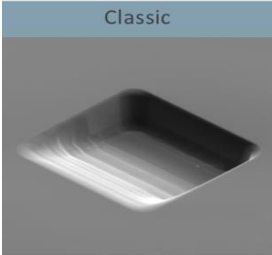
1.4 nm  
at 1 keV

0.9 nm  
at 15 keV

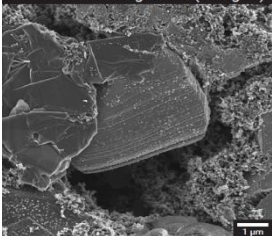


Classic

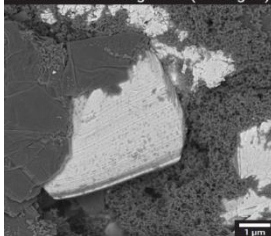
With SmartMill



Multidetector with grid OFF (SE signal)

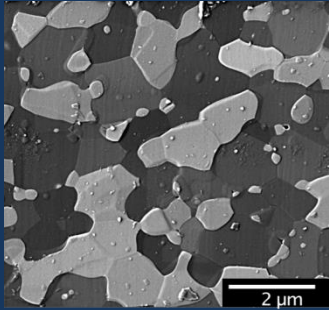


Multidetector with grid ON (BSE signal)

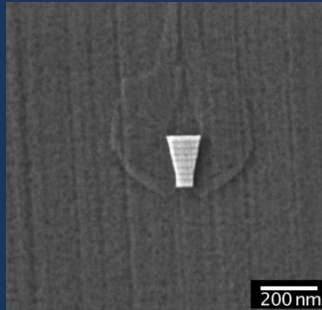


# 1. Universality in sample imaging field-free UHR at low kV

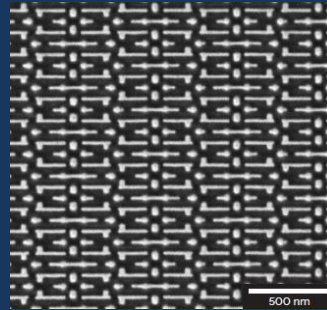
- High resolution imaging of magnetic samples at low keV
- High resolution imaging of non-conductive samples at low keV



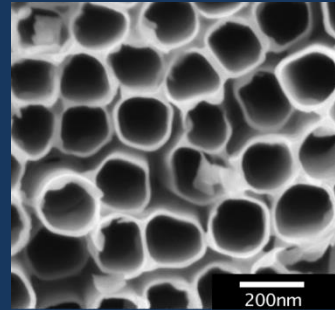
Surface of a Read/Write magnetic head image at 2keV



Magnetic write head imaged at 2keV

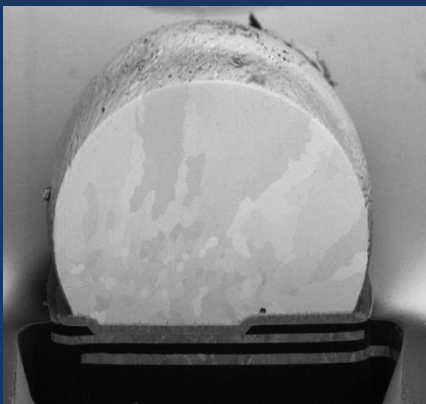


14nm IC delayed to V0-M0 layer at 2keV

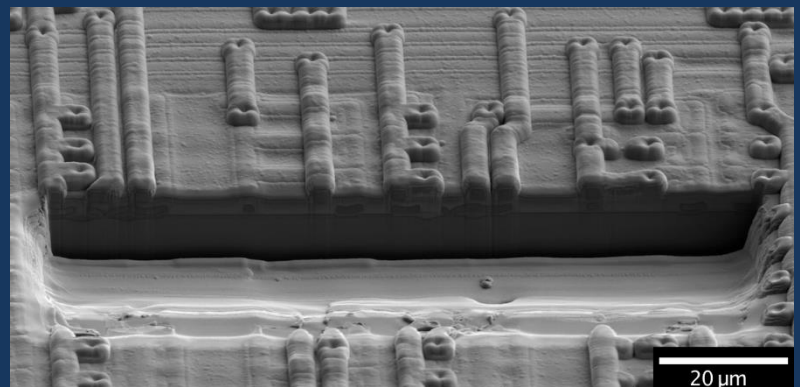


TiO<sub>2</sub> nanotubes imaged at 500eV

# 2. Large-area cross-sections completed in half time compared to conventional Ga-FIB (Ion Beam current up to 100nA)

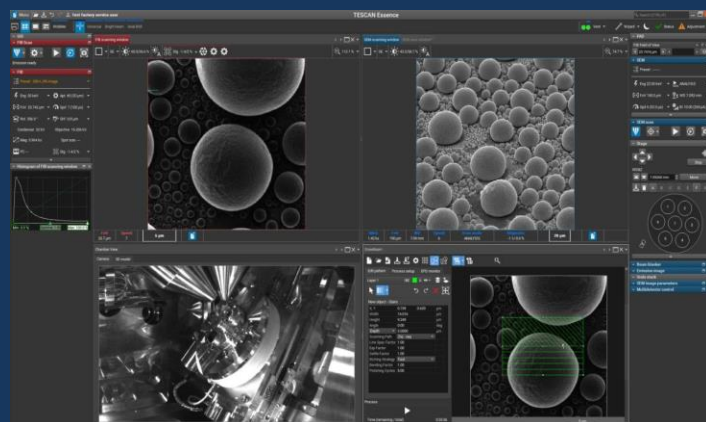


< 110μm diameter of solder ball completed in 60minutes at Ion beam current 100nA



100 μm × 30 μm × 20 μm completed in 20 minutes at Ion beam current 80nA

# 3. New TESCAN Software Platform



- Simplified UI for fast access to main functions
- Easy-to-learn, new user is productive within a short time
- Compatible with multi-user environment
- Maximum Productivity for all users